

HVD372B

Variable Capacitance Diode for VCO

REJ03G0503-0100

(Previous: ADE-208-957)

Rev.1.00 Jan 24, 2005

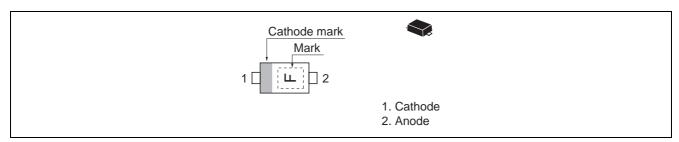
Features

- High capacitance ratio. (n = 2.00 min)
- Good linearity of C-V curve.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Renesas Code	Previous Code	
HVD372B	F	PUSF0002ZB-A	SFP	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 15 V
	I _{R2}	_	_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	15.0	_	17.0	pF	V _R = 1 V, f = 1 MHz
	C ₄	7.00	_	8.50		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	2.00	_	_	_	C ₁ / C ₄
Series resistance	rs	1		0.40	Ω	V _R = 1 V, f = 470 MHz

Note: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

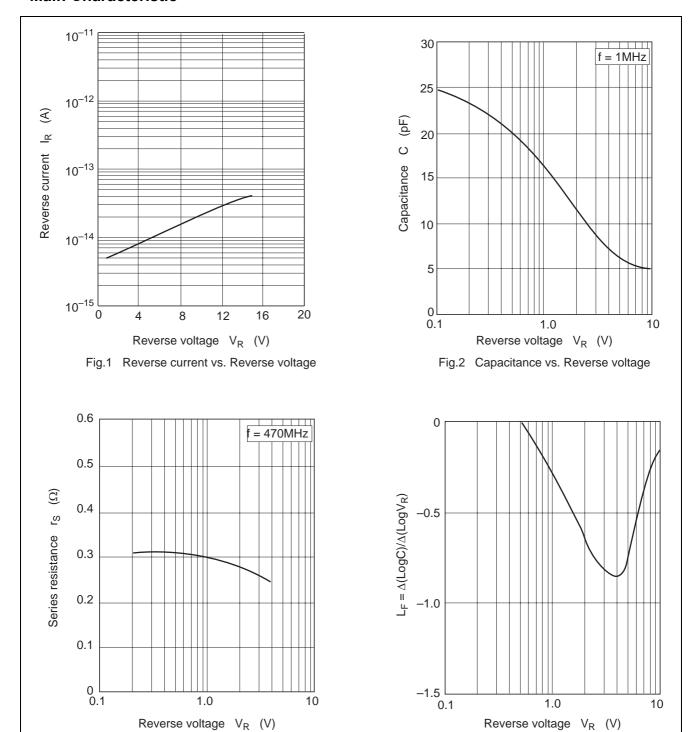
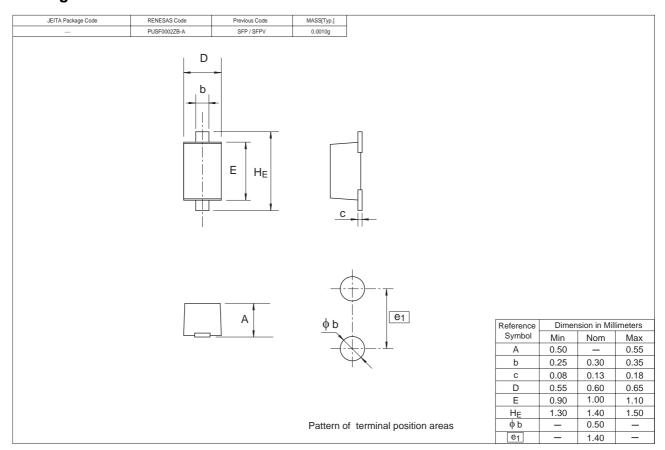


Fig.3 Series resistance vs. Reverse voltage

Fig.4 Linearity factor vs. Reverse voltage

Package Dimensions



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